

Case Docket No. ASMJP.137AUS

Date: November 21, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s)

Yasuyoshi Hyodo, et al.

App. No.

10/644,195

Filed

August 20, 2003

For

METHOD OF FORMING

SILICON-CONTAINING

INSULATION FILM HAVING

LOW DIELECTRIC

CONSTANT AND LOW FILM

STRESS

Group Art Unit:

Unknown

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

November 21, 2003 (Date)

Katsuhiro Arai, Reg. No. 43,315

TRANSMITTAL LETTER

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

ATTENTION: MAIL STOP MISSING PARTS

Dear Sir:

In response to the Notice to File Missing Parts of Application Under 37 CFR 1.53(f), which was mailed by the Office on November 14, 2003, enclosed are:

- (X) An executed Declaration by Inventor(s).
- (X) A Power of Attorney Form and Copy of Assignment.
- (X) A Notice to File Missing Parts.
- (X) Return prepaid postcard.
- (X) Fees as calculated below:

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SURCHARGE(1051) 37 CFR 1.16(e)	\$ + 130
TOTAL FEES SUBMITTED HEREWITH	\$ 130

- (X) A check in the amount of \$130.00 to cover the above fees is enclosed.
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, now or in the future, or credit any overpayment, to Account No. 11-1410.

Katsuhiro Arai

Registration No. 43,315

Agent of Record

Customer No. 20,995

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